

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

PESD0603MS18-MS

Product specification


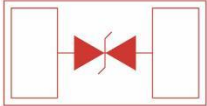
FEATURES

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<100nA)
- Fast response time(<1ns)
- Bi-directional,single line protection
- IEC 61000-4-2 (ESD Air): 15kV
- IEC 61000-4-2 (ESD Contact): 8kV

Applications

- USB 3.0/3. 1
- HDMI 1.3/ 1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
	
0603	

Limiting Values(TA = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
VESD	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	8	kV
		IEC 61000-4-2; Air Discharge	-	15	kV
TA	Operating Temperature Range	-	-40	90	°C
Tstg	Storage Temperature Range	-	-55	125	°C

ELECTRICAL CHARACTERISTICS (Tamb=25°C)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
VDC	Continuous Operating Voltage	-	-	-	18	V
VT	Trigger Voltage	IEC61000-4-2 8kV contact discharge	-	450	-	V
VC	Clamping Voltage	IEC61000-4-2 8kV contact discharge	-	40	-	V
IL	Leakage Current	DC 18V shall be applied on component	-	-	100	nA
CJ	Capacitance	Measured at 10MHz	-	0.05	-	pF

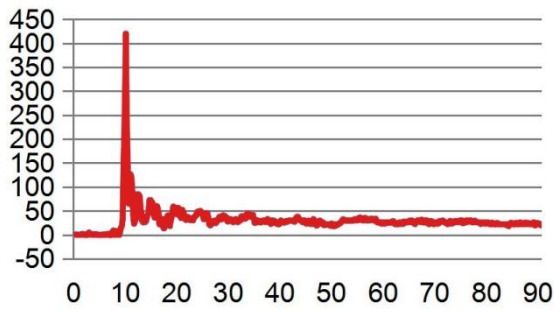


Fig. 1 Typical ESD Response
 (IEC 61000-4-2, 8kV contact discharge)

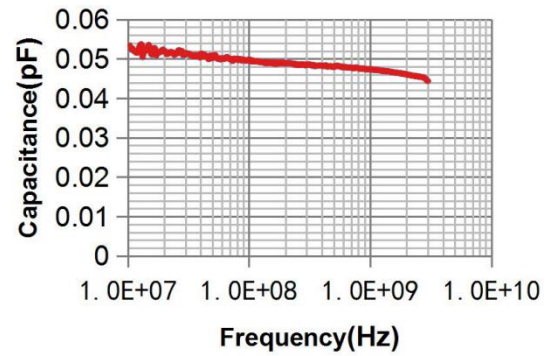
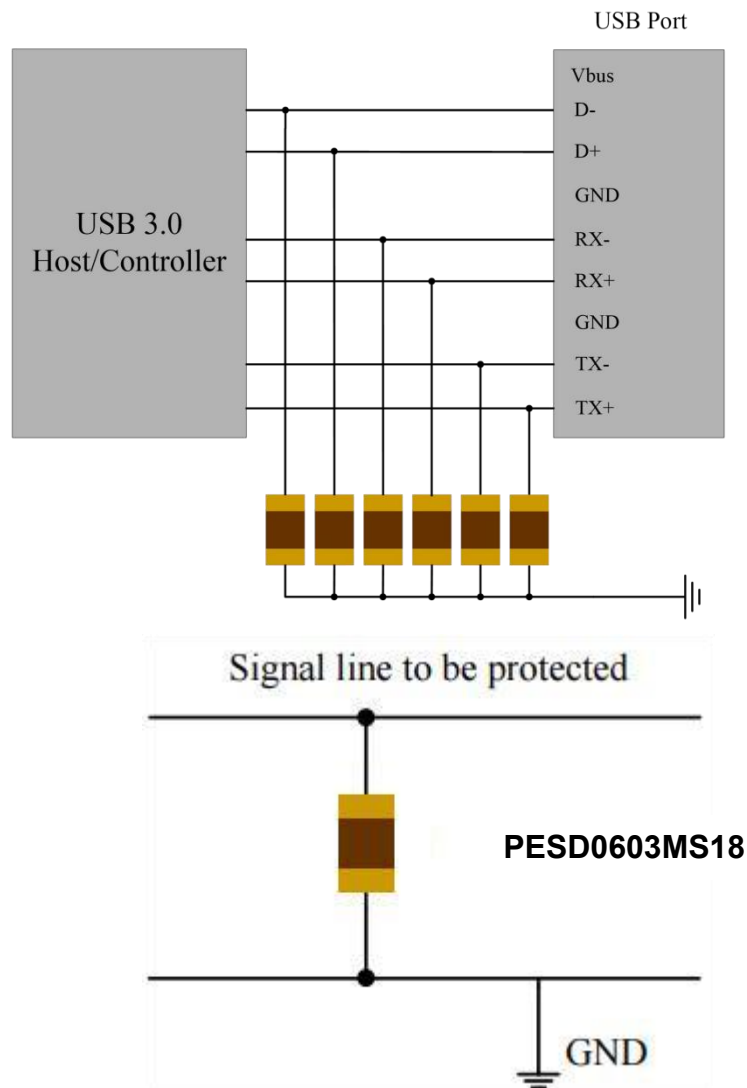


Fig.2 Typical Device Capacitance VS. Frequency

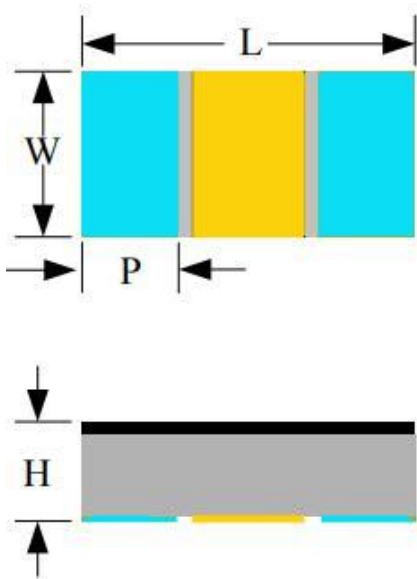
ESD Protection for Signal Line

The PESD is designed for the protection of one bidirectional data line from ESD damage.

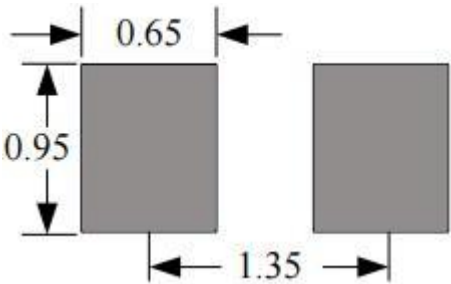
- Place the PESD as close to the input terminal or connector as possible.
- Minimize the path length between the PESD and the protected signal line.
- Use ground planes whenever possible.



PACKAGE MECHANICAL DATA



Recommended Solder Pad Footprint



Notes:
This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters	
	Min	Max
L	1.45	1.75
W	0.70	0.95
P	0.20	0.50
H	0.26	0.46

REEL SPECIFICATION

P/N	PKG	QTY
PESD0603MS18-MS	0603	5000

Attention

■ Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.

■ MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specification of any and all MSKSEMI Semiconductor products described or contained herein.

■ Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

■ MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

■ In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

■ No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.

■ Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.

■ Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.